CLAIMS

[Claim 1]

A taping apparatus configured to transfer a carrier tape in which electronic components are put in pockets at an insertion position, to guide a cover tape to an upper side of the carrier tape at a joining position on a downstream side of the insertion position, and to bond the cover tape to the carrier tape from above at a bonding position so as to seal the electronic component, the taping apparatus comprising:

a pressing member that presses one of the carrier tape and the cover tape against the other of the carrier tape and the cover tape at the bonding position so as to perform bonding;

a transfer mechanism that transfers the carrier tape in a state where the carrier tape is provided with a tension region along a range from an upstream side of the joining position to a downstream side of the bonding position;

an upper guide disposed above the tension region; and

a push-up mechanism that presses the tension region entirely or partially against the upper guide from below,

wherein the carrier tape is formed with the pockets at equal pitches in a longitudinal direction, and first and second flat portions arranged in higher positions than bottoms of the pockets are provided respectively on both sides of the pocket in a width direction,

wherein the push-up mechanism includes a contact portion that contacts the tension region from below, wherein portions of the contact portion, which are located directly below the first and second flat portions of the carrier tape, projects upward

as compared to a portion located directly below the pocket, and respectively contact the first and second flat portions.

[Claim 2]

The taping apparatus according to claim 1, wherein the contact portion does not contact the bottoms of the pockets.

[Claim 3]

The taping apparatus according to claim 1 or 2, wherein the push-up mechanism includes an elastic body configured to apply an upward force to the contact portion.